

FIRST ANNOUNCEMENT AND CALL FOR PAPERS

2019 SYMPOSIUM ON VLSI CIRCUITS

Pushing the Limits of Semiconductors for United and Connected World

RIHGA Royal Hotel Kyoto, Japan
 Sunday – Friday, June 9-14, 2019
 June 9 Sunday Workshop
 June 10 Short Course
 June 11-13 Technical Sessions
 June 14 Friday Forum

Paper Submission Deadline: 23:59 JST Monday, January 28, 2019
 For detail, please visit: www.vlssymposium.org

Symposium Scope

The Circuits Symposium is placing special emphasis on several Innovative System focus areas, and encourages paper submissions on:

- Machine and deep learning
- Internet of Things
- Industrial electronics
- Big Data management
- Biomedical Applications
- Robotics and autonomous transportation

New focus sessions comprising invited and contributed papers will be offered.

In addition, submissions are welcomed in all of the following circuits areas:

- Processors, SoCs, and Machine Learning
- Digital circuits, signal integrity, and IOs
- Hardware security
- Memory circuits, architectures, and interfaces
- Biomedical circuits
- Sensors, imagers, and display circuits
- Power conversion circuits
- Analog, amplifier and filter circuits
- Wireless receivers and transmitters
- Data converters
- Frequency generation and clock circuits
- Wireline receivers and transmitters

Call for Workshop

The call for proposals for the Sunday Workshop is now open. You organize the workshop, VLSI provides the venue. Check the details in www.vlssymposium.org

Short Course

A full day Short Courses will offer in-depth lectures on the topics of highest interest to the VLSI community given by distinguished experts from industry and academia.

Joint Circuits and Technology Focus Sessions

Joint circuits and technology focus sessions will be offered in the following special topics of joint interest:

- **Tech & system for new computing:** design and technology for enabling high performance AI, neuromorphic computing, beyond Von Neumann architecture, etc.
- **Design and technology for scaling extension:** design for manufacturing, process-design co-optimization, on-die monitoring of variability and reliability
- **Embedded memory technology and design:** SRAM, DRAM, Flash, PCRAM, ReRAM, MRAM, etc.
- **3D and heterogeneous integration:** power and thermal management, inter-chip communication, SiP architectures and applications

Paper Submission

Prospective authors must submit two-page camera-ready papers and abstracts using the Symposia's website, www.vlssymposium.org. Accepted papers will be published as submitted, with **no revisions permitted**. Authors must follow detailed instructions provided within the "Authors" section of the website, including the Authors' Guide and Pre-publication Policy. Extended versions of selected papers from the Symposium will be published in a **Special Issue of the IEEE Journal of Solid-State Circuits**.

Best Student Paper Award

Best Student Paper Award selection will be based on quality and presentation of the paper at the Symposium. The winning student will be presented a monetary award and a certificate at the 2020 Symposium opening session. **The student must be enrolled as a full-time student at the time of submission, be the leading author and presenter of the paper**, and indicate when submitting the paper that the paper should be considered for the award.

Secretariat for VLSI Symposia

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